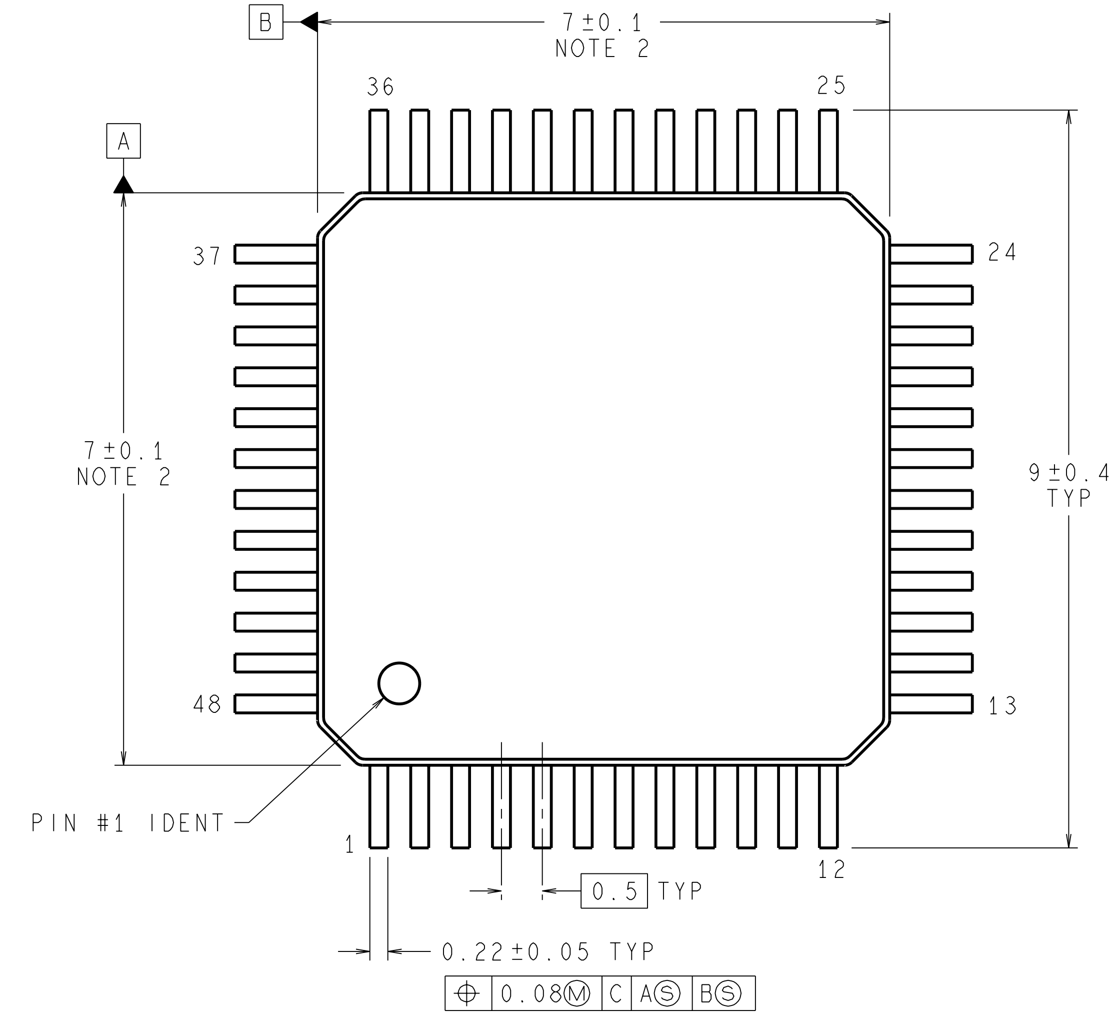
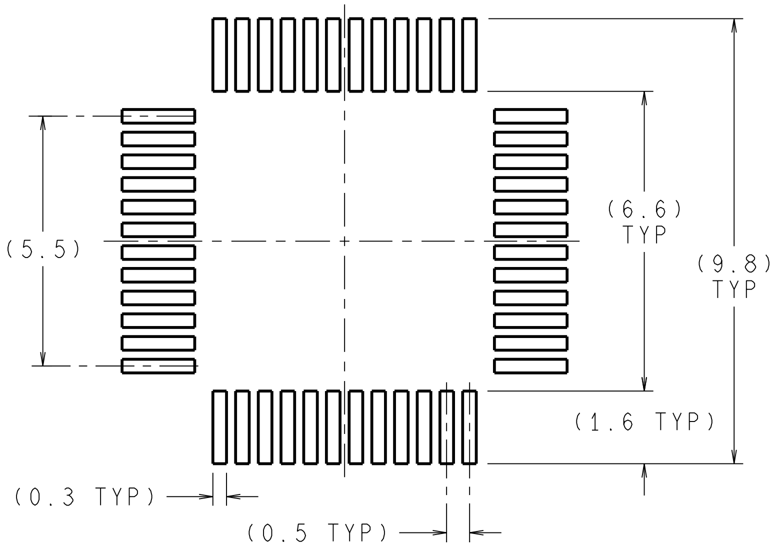
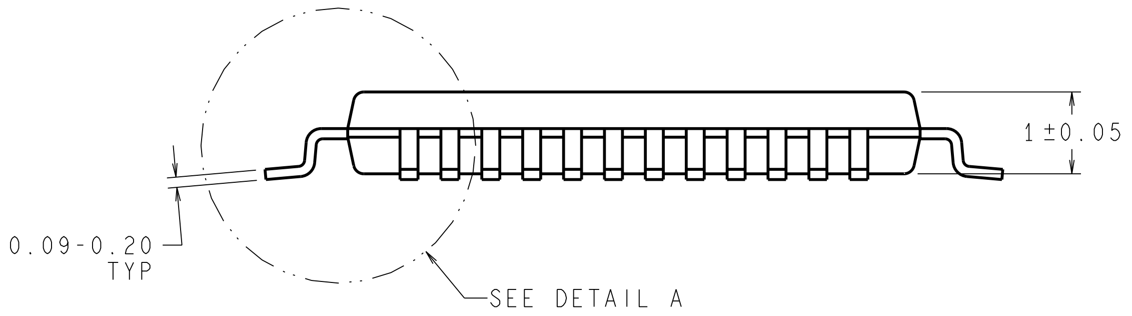
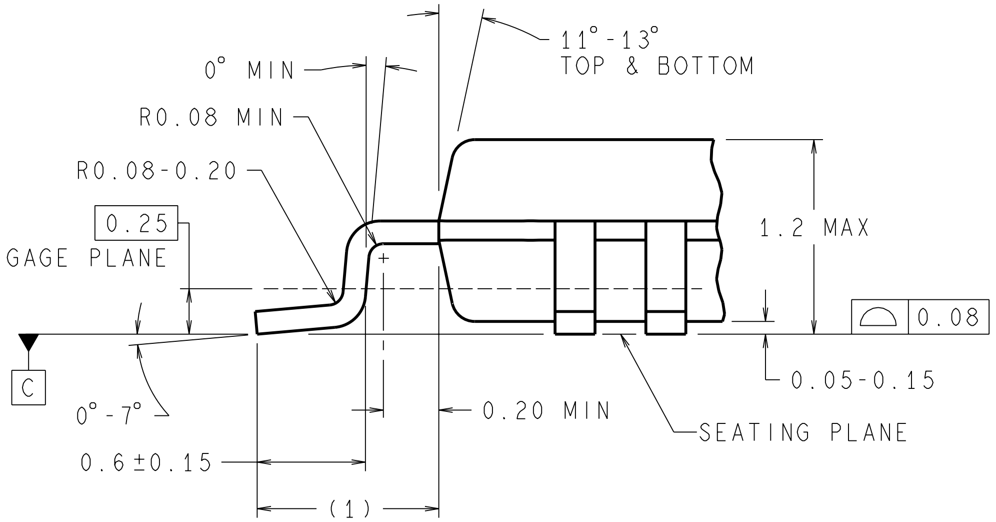
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12451	04/21/2000	TL/RW





LAND PATTERN RECOMMENDATION





DETAIL A

TYP, SCALE: 40X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH:
   7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
   THICKNESS ON COPPER.
2. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
   MAXIMUM ALLOWABLE MOLD PROTRUSION 0.15mm PER SIDE.
3. REFERENCE JEDEC REGISTRATION MS-026, VARIATION ABC,
   DATED FEBRUARY 1999.

APPROVALS	DATE
DRAWN T. LEQUANG	04/21/2000
DFTG. CHK. MARTA SUCHY	04/21/2000
ENGR. CHK. RANDY WALBERG	04/21/2000

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

TQFP, JEDEC METRIC, 7 X 7 X 1mm, 48 LEAD, 0.5mm PITCH

PROJECTION
INCH
[MM]

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	(SC)MKT-VBC48A	A

FORMERLY: N/A
SHEET 1 of 1